



ATTEND
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SPECIFICATION AND PERFORMANCE

SERIES:
DDR Series

FILE:
DDR Series_spec

DATE:
2013/01/04

Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of DDR Series.

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIAL AND FINISH

INSULATOR	Material	Housing: LCP UL94V-0 Black
	CONTACT	Contact: Phosphor Bronze C5210
SHELL OR COVER	Plating	Contact Area: Gold Flash
	Material	Latch: Stainless Steel SUS301
RATING	Plating	
	Current Rating : 0.5A Voltage Rating : 25V AC Operating Temperature : -40~+85°C Storage Temperature: -40°C to +90°C	

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ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	Initial: 60 mΩ Max. Final: 80 mΩ Max.	Solder connectors on PCB and mate them together, measure by applying closed circuit current of 10mA maximum at open circuit voltage of 20mV maximum.
Insulation Resistance	Initial: 500MΩ Min. Final: 100MΩ Min.	Mate connectors, apply 100V DC (rms.) between two adjacent contacts for one minutes. [MIL STD. 202F, Method 302]
Dielectric Withstanding Voltage	125VAC for 1 minutes. Leak current: 0.5 [mA] Max.	Mate connectors, apply 125V AC (rms.) between two adjacent contacts for one minutes. [MIL STD. 202F, Method 301]

MECHANICAL

Item	Requirement	Test Condition
Durability	No Damage	Solder connectors on PCB, then repeat mating and unmating 25 cycles along the mating axis.
Contact Retention Force	1 N/pos. Min	Place a connector on the push-pull machine, then apply a force on a contact head and push the contact to the opposite direction of the contact insertion at the speed of 25±3mm/min. Measure the force when the contact dislodges from insulator.
Latch Spring Retention Force	8 N/Pos. Min	Place a connector on the push-pull machine, then apply a force on a contact head and push the latch spring to the opposite direction of the latch spring insertion at the speed of 25±3mm/min. Measure the force when the latch spring dislodges from insulator.

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Vibration	No electrical discontinuity greater than 1 μ second shall occur.	Solder connectors on PCB and mate them together, subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1mA current during test. Amplitude: 1.52 mm P-P Sweep Frequency.: 10 - 55 - 10 Hz /min [MIL STD. 202F, Method 201A]
Shock	No electrical discontinuity greater than 1 μ sec shall occur.	Solder connectors on PCB and mate them together, subject to the following shock conditions, 3 shocks shall be period along 3 mutually perpendicular axes, passing DC 1mA current during the test. (Total of 18 shocks) Test Pulse : Half sinusoidal-Peak 490 m/s ² (50G) Duration: 11 msec. [MIL STD. 202F, Method 213A]

ENVIRONMENTAL

Item	Requirement	Test Condition
Heat Resistance	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, expose to 85 \pm 2 $^{\circ}$ C for 96hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. [MIL STD. 202F, Method 108A]

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Cold Resistance	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, expose to $-40\pm 3^{\circ}\text{C}$ for 96hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.
Thermal Shock	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, subject to the following conditions for 5 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2 hours, after which the specified measurements shall be performed. Heat Cycle: a) -40°C (30min.) b) $+85^{\circ}\text{C}$ (30min.) Transit time shall be within 3 min
Humidity	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, expose to the defined environment condition for 10 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2 hours, after which the specified measurements shall be performed.

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Salt Spray	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, subject to the following salt mist. Upon completion of the exposure period, salt deposits shall be removed by gentle wash or dip in running water, after which the specified measurements shall be performed. NaCl solution: a) Concentration: 5±1 % b) Spray time: 48±4h c) Ambient Temperature : 35±1°C
SO2 Gas	Detrimental damage affecting to the performance shall not occur.	Solder connectors on PCB and mate them together, expose to 10ppm SO2 gas, ambient temperature 25±2 °C for 24 Hours.

SOLDER ABILITY

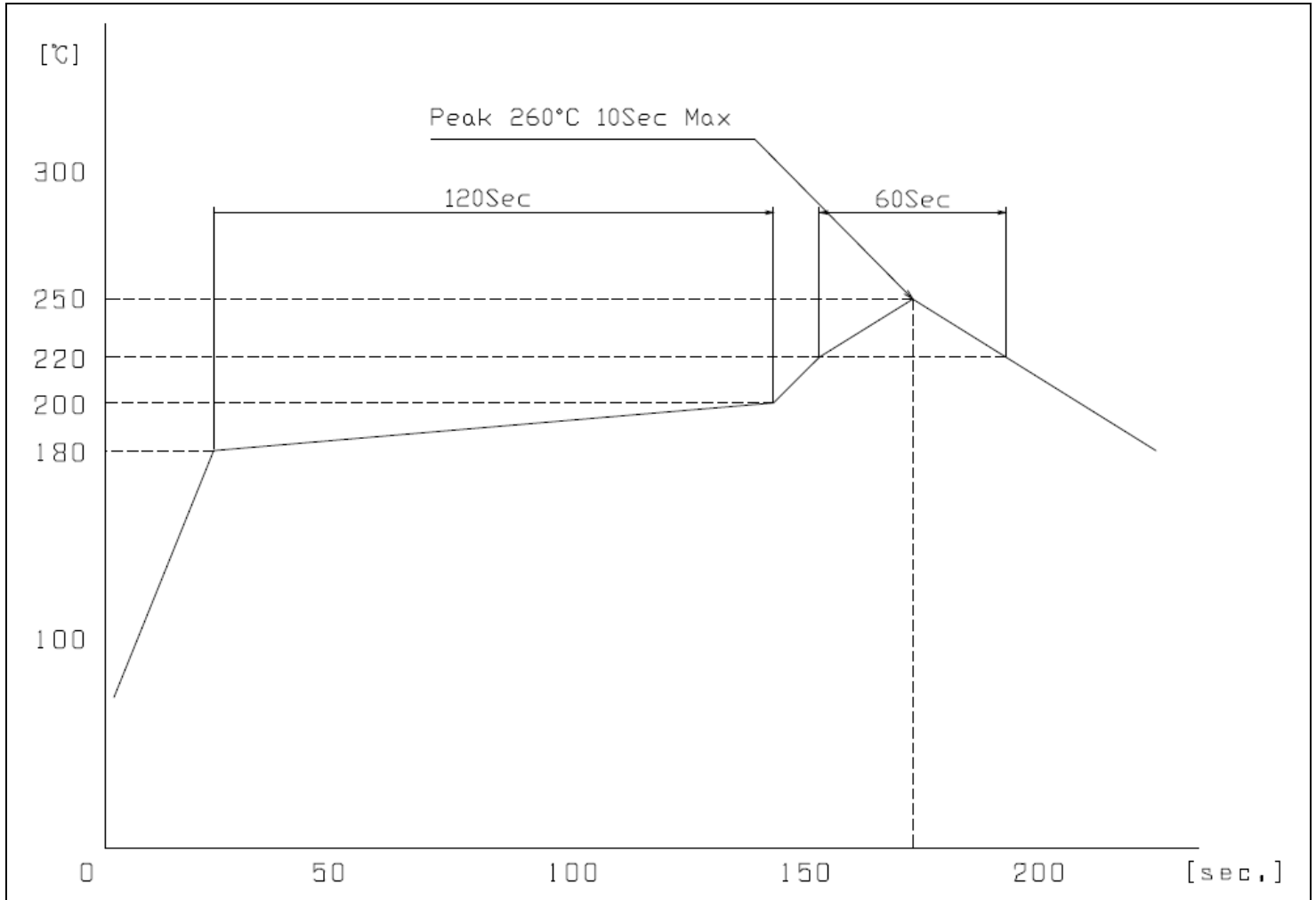
Item	Requirement	Test Condition
Solderability	More then 95% of the dipped surface shall be wet evenly with new solder.	The solder time of connector in the solder bath at 230±5°C for 3±0.5 sec. After immersing solder tine in the flux for 5 to 10 seconds
Solder heat resistance	Detrimental damage affecting to the performance shall not occur.	180~200°C for 120 seconds. Max 220°C for 60 sec. Max Peak : 255±5°C 10 sec. Max



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Test Sequence

試驗項目 Test Item		Group													
		A	B	C	D	E	F	G	H	I	J	K	L	M	N
1	Examination of Product	1,5	1,4	1	1	1,5	1,5	1,5	1,5	1,5	1,6	1,5	1,5	1,3	1,3
2	Contact Resistance	2	3			2,4	2,4	2,4	2,4	2,4	2,4	2,4	2,4		
3	Dielectric withstanding voltage	4													
4	Insulation Resistance	3									5				
5	Durability		2												
6	Contact Retention Force			2											
7	Latch Spring Retention Force				2										
8	Vibration					3									
9	Shock						3								
10	Heat Resistance							3							
11	Cold Resistance								3						
12	Thermal Shock									3					
13	Humidity										3				
14	Salt Spray											3			
15	SO ² Gas												3		
16	Solderability													2	
17	Solder Heat Resistance														2
Connector		1	2	2	5	2	2	2	2	2	2	2	2	2	2
Mating PCB (set)		1	2	2	2	2	2	2	2	2	2	2	2	2	2
		Quantities of Samples													

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